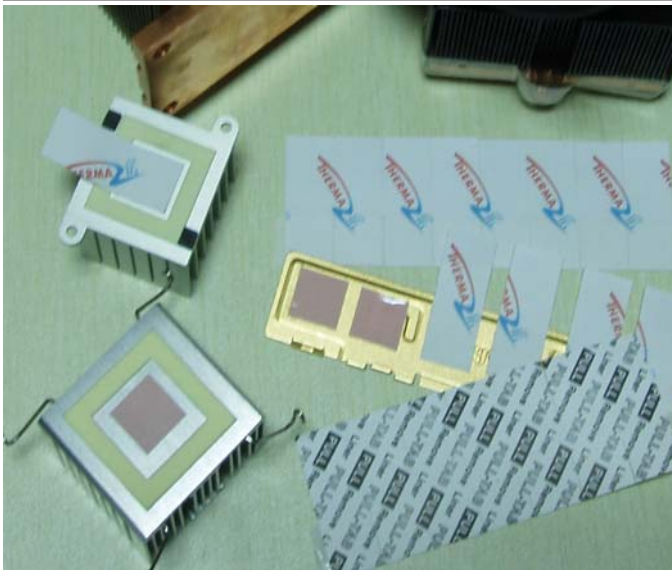


Low Melting Point Thermal Interface Materials



For Lowest Thermal Resistance :

- 0.024°C-in² /W thermal resistance
- Naturally tacky at room temperature, no adhesive required
- No heat sink preheating required

Applications Include:

- High Frequency Microprocessors
- Notebook and Desktop PCs
- Computer Servers
- Memory Modules
- Cache Chips
- IGBTs

TIC800P series is low melting point thermal interface material. At 50°C, TIC800P series begins to soften and flow, filling the microscopic irregularities of both the thermal solution and the integrated circuit package surface, thereby reducing thermal resistance. TIC800P series is a flexible solid at room temperature and freestanding without reinforcing components that reduce thermal performance.

TIC800P Series shows no thermal performance degradation after 1,000 hours @ 130°C, or after 500 cycles, from -25°C to 125°C. The material softens and does not fully change state resulting in minimal migration (pump out) at operating temperatures.

Product Name	TIC803P	TIC805P	Test Method
Color	Pink	Pink	Visual
Thickness	0.003" (0.076mm)	0.005" (0.127mm)	
Thickness Tolerance	±0.0006" (±0.016mm)	±0.0008" (±0.020mm)	
Density	2.2g/cc		Helium Pycnometer
Temperature range	-25°C~125°C		
Phase Change Softening Temperature	50°C~60°C		
"Burn In" Temperature	70°C for 5 minutes		
Thermal Conductivity	0.95 W/mK		ASTM D5470 (modified)
Thermal Impedance @ 50 psi(345 KPa)	0.021°C-in ² /W 0.14°C-cm ² /W	0.024°C-in ² /W 0.15°C-cm ² /W	ASTM D5470 (modified)

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